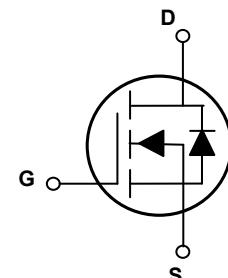
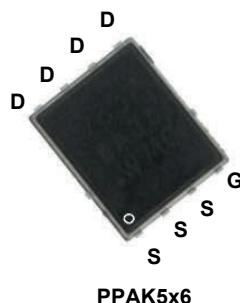


### Main Product Characteristics

BV <sub>DSS</sub>	40V
R <sub>DS(ON)</sub>	5mΩ (Max)
I <sub>D</sub>	96A



Schematic Diagram

### Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



### Description

The GSFP4005SF utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies and a wide variety of other applications.

### Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Max.	Unit
Drain-Source Voltage	V <sub>DS</sub>	40	V
Gate-Source Voltage	V <sub>Gs</sub>	±20	V
Drain Current	I <sub>D</sub>	96	A
		61	A
		27	A
		22	A
Pulsed Drain Current <sup>2</sup>	I <sub>DM</sub>	192	A
Total Power Dissipation <sup>3</sup>	P <sub>D</sub>	78	W
		6.3	W
Thermal Resistance Junction-to-Ambient <sup>1,4</sup>	R <sub>θJA</sub>	20	°C/W
Thermal Resistance Junction-to-Case	R <sub>θJC</sub>	1.6	°C/W
Junction and Storage Temperature Range	T <sub>J/T<sub>STG</sub></sub>	-55 to +150	°C

**Electrical Characteristics** ( $T_J=25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
<b>On / Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	40	-	-	V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}}=40\text{V}, V_{\text{GS}}=0\text{V}, T_c=25^\circ\text{C}$	-	-	1	$\mu\text{A}$
Gate-Body Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	$\pm 100$	nA
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	1.5	-	2.5	V
Static Drain-Source on-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=20\text{A}$	-	4.0	5.0	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=16\text{A}$	-	5.7	7.5	
<b>Dynamic and Switching Characteristics</b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}}=20\text{V}, V_{\text{GS}}=0\text{V}, F=1\text{MHz}$	-	4100	-	pF
Output Capacitance	$C_{\text{oss}}$		-	280	-	
Reverse Transfer Capacitance	$C_{\text{rss}}$		-	275	-	
Total Gate Charge	$Q_g$	$V_{\text{GS}}=10\text{V}, V_{\text{DS}}=20\text{V}, I_{\text{D}}=20\text{A}$	-	78	-	nC
Gate Source Charge	$Q_{\text{gs}}$		-	11.5	-	
Gate Drain Charge	$Q_{\text{gd}}$		-	18	-	
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{GS}}=10\text{V}, V_{\text{DD}}=20\text{V}, I_{\text{D}}=20\text{A}, R_{\text{GEN}}=3\Omega$	-	27.8	-	nS
Turn-on Rise Time	$t_r$		-	12.8	-	
Turn-off Delay Time	$t_{\text{d}(\text{off})}$		-	96	-	
Turn-off Fall Time	$t_f$		-	24	-	
<b>Source-Drain Ratings and Characteristics</b>						
Diode Forward Voltage	$V_{\text{SD}}$	$I_{\text{S}}=20\text{A}, V_{\text{GS}}=0\text{V}$	-	0.8	1.2	V
Maximum Body-Diode Continuous Current	$I_{\text{S}}$	-	-	-	96	A

Notes:

- The value of  $R_{\theta_{\text{JA}}}$  is measured with the device mounted on lin2 FR-4 board with 2oz.Copper,in a still air environment with  $T_A=25^\circ\text{C}$ . The value in any given application depends on the user's specific board design.
- Single pulse width limited by junction temperature  $T_{J(\text{MAX})}=150^\circ\text{C}$ .
- The power dissipation  $P_D$  is based on  $T_{J(\text{MAX})}=150^\circ\text{C}$ , using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.
- The  $R_{\theta_{\text{JA}}}$  is the sum of the thermal impedance from junction to case and case to ambient.

## Typical Electrical and Thermal Characteristic Curves

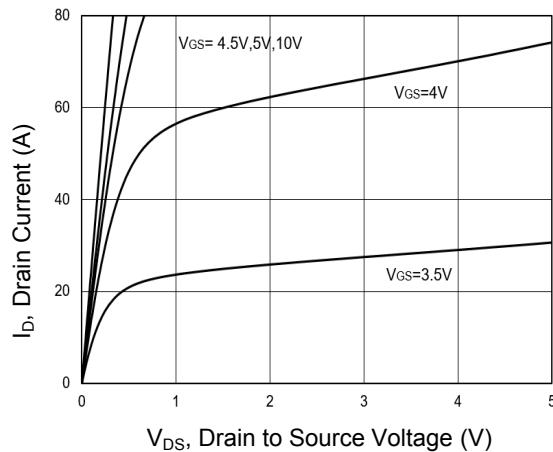


Figure 1. Output Characteristics

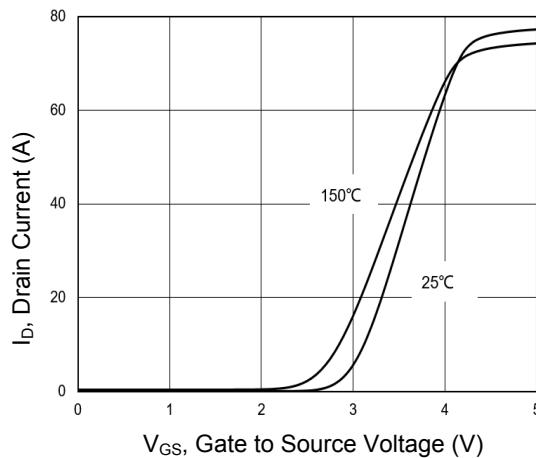


Figure 2. Transfer Characteristics

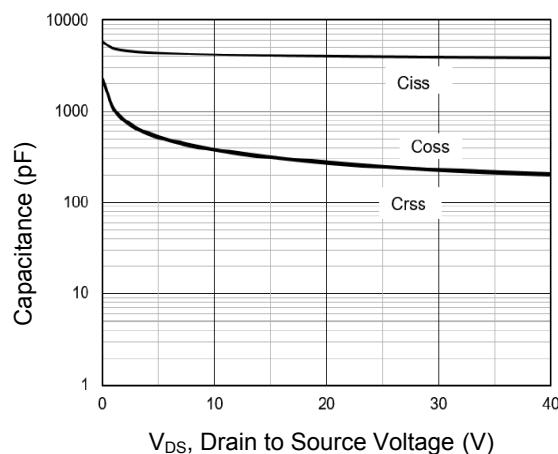


Figure 3. Capacitance Characteristics

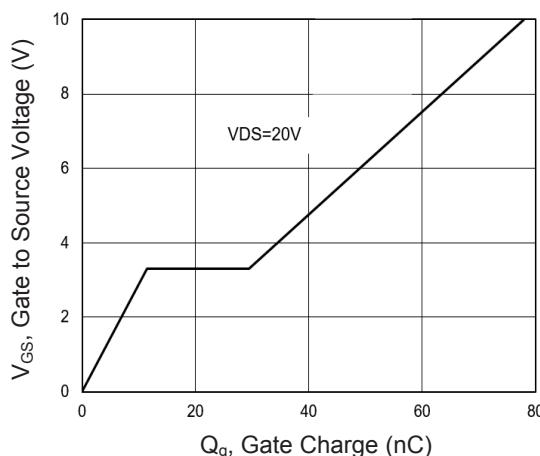


Figure 4. Gate Charge

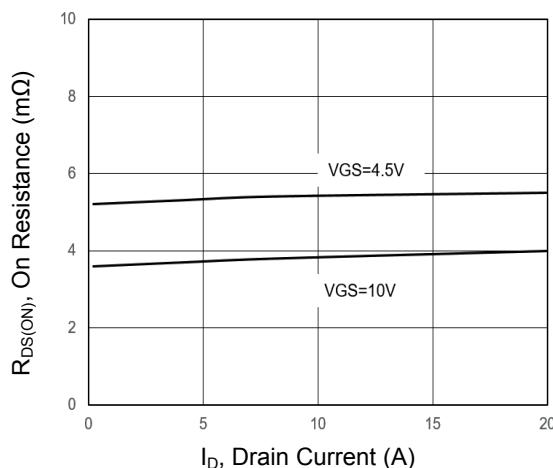


Figure 5. Drain-Source on Resistance

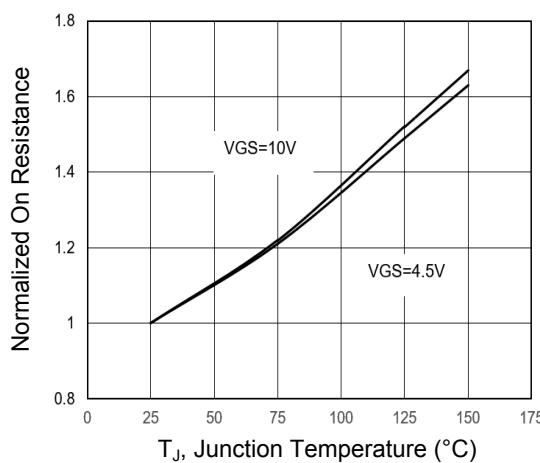
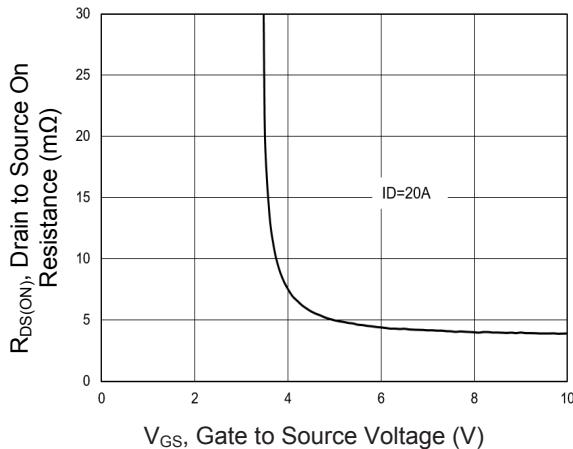
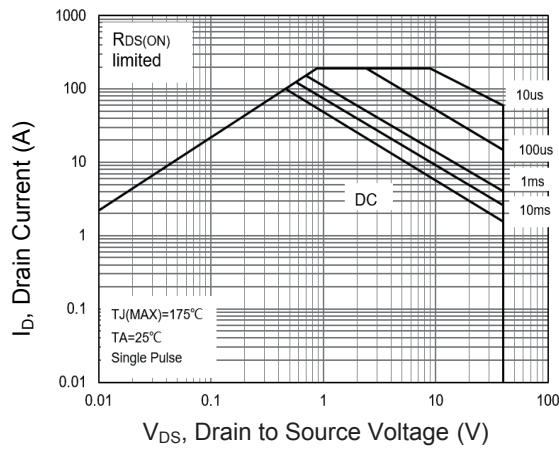


Figure 6. Normalized  $R_{DS(ON)}$  vs.  $T_J$

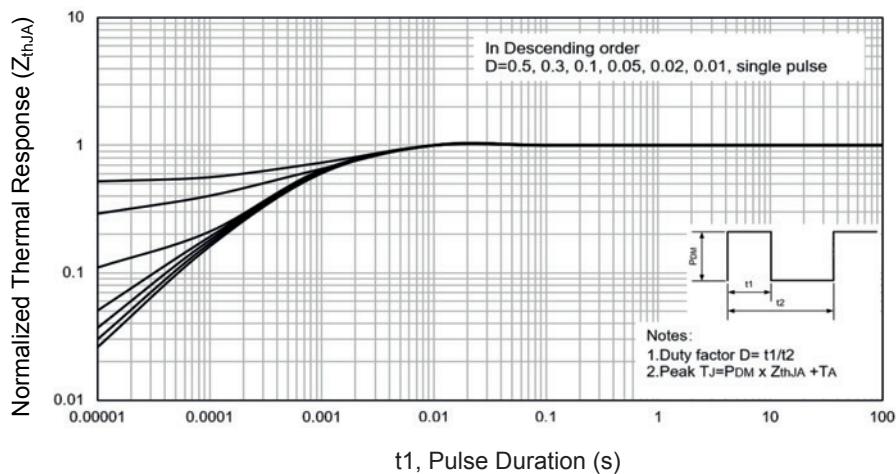
## Typical Electrical and Thermal Characteristic Curves



**Figure 7. Typical Drain to Source ON Resistance vs. Gate Voltage and Drain Current**

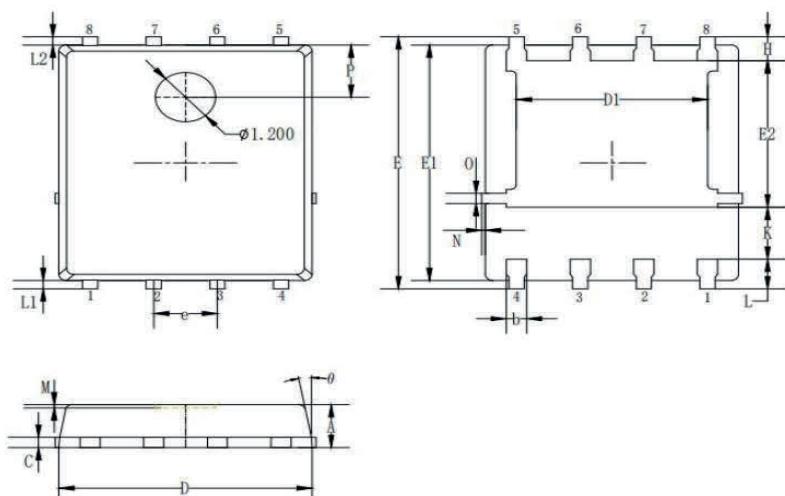


**Figure 8. Safe Operation Area**



**Figure 9. Maximum Effective Transient Thermal Impedance, Junction-to-Case**

### Package Outline Dimensions (PPAK5x6)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.90	1.20	0.035	0.047
b	0.35	0.50	0.014	0.020
c	0.20	0.35	0.008	0.014
D	4.90	5.20	0.193	0.205
D1	3.72	3.92	0.146	0.154
E	6.00	6.30	0.236	0.248
E1	5.60	5.90	0.220	0.232
E2	3.47	3.67	0.137	0.144
e	1.27 BSC		0.050 BSC	
H	0.48	0.68	0.019	0.027
K	1.17	1.37	0.046	0.054
L	0.64	0.84	0.025	0.033
L1/L2	0.20 REF		0.008 REF	
θ	8°	12°	8°	12°
M	0.08 REF		0.003 REF	
N	0	0.15	0.000	0.006
O	0.25 REF		0.010 REF	
P	1.28 REF		0.050 REF	

### Order Information

Device	Package	Marking	Carrier	Quantity
GSFP4005SF	PPAK5x6	N4005SF5	Tape & Reel	5,000pcs / Reel

For more information, please contact us at: [inquiry@goodarksemi.com](mailto:inquiry@goodarksemi.com)